



Chip Module Production

Hidden Precision.
Visible Performance.

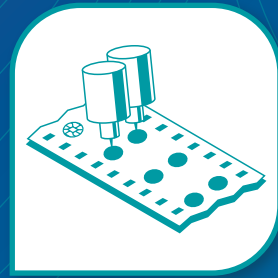
 www.macksmatec.com

MackSm&Tec[®]

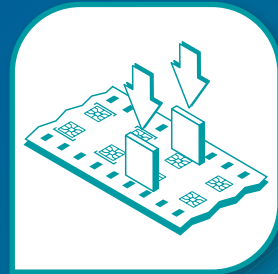
MACHINES THAT THINK AHEAD.

MACK
GROUP

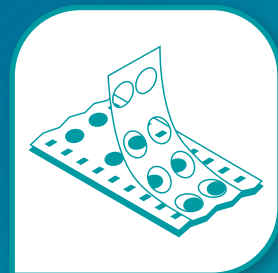
MackSmaTec Smart Card Solutions – Equipment for module preparation, testing and personalization



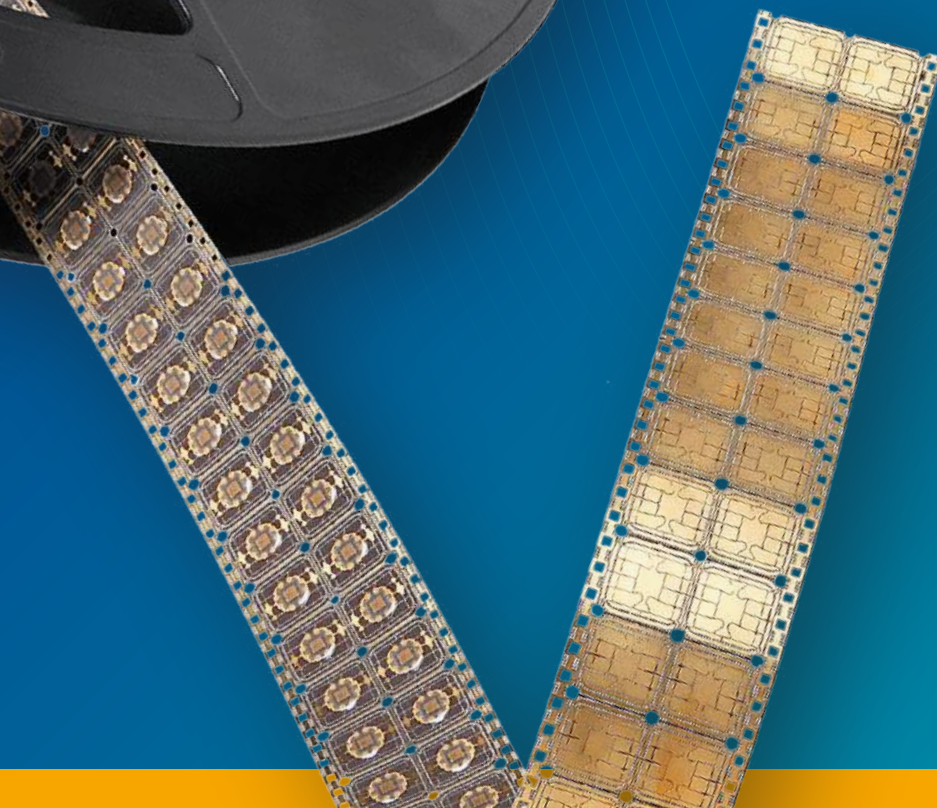
PowerSeal
Encapsulation



PowerTest
Module Testing



GTL 700
Glue Tape
Lamination



PowerSeal

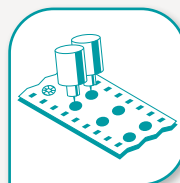
Chip Module Encapsulation



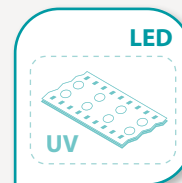
PowerSeal is the solution for encapsulation of ICs on 35 mm module tape. Extremely compact, extremely powerful.

+ Benefits and Features:

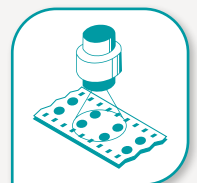
- » Fill or dam & fill process
- » Programmable movement of dosing heads
- » Heating of module tape & dosing heads
- » Visual process control
- » Additional glob-top form inspection
- » Competitiveness by combining a substantially increased throughput at a very attractive price level



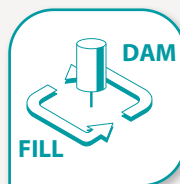
Cast Resin
Dispensing
12/16 Fold
1/2 Heads



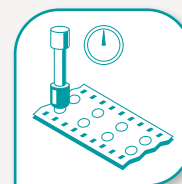
Curing Unit -
UV / UV-Led



Optical
Inspection -
Glob Top



Changeability
Of Dam Head
For Fill



Height Test -
Mechanical
Random

PowerTest

Chip Module
Testing/Initialization/
Inspection



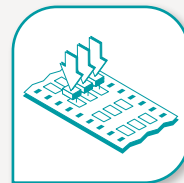
PowerTest is a sophisticated chip module testing and encoding system for 35 mm module tapes.

+ Benefits and Features:

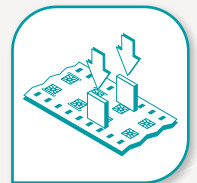
- » Reel to reel system for chip module test, initialization and pre-personalization
- » Contact, contactless and Dual Interface modules can be processed on one machine
- » High speed transport system, including reject hole detection at input and output
- » Reject hole punch for faulty chip modules
- » Modular design and graphic user interface
- » Open platform for integration of customer test hardware and software



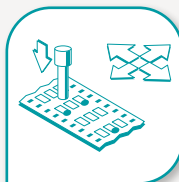
Contact Unit
& Basic/Parameter
Test Up To
128 Heads



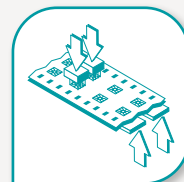
Contactless Unit
& Basic/Parameter
Test Up To 48 Heads



Disconnect
Station



Reject Hole
Punching



Dual Interface Unit
& Basic/Parameter
Test Up To
32/32 Heads



Optical
Inspection

GTL 700

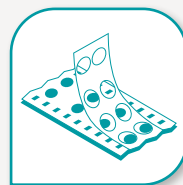
Glue Tape Lamination



GTL700 is a highly reliable and flexible solution for glue tape lamination of chip module tapes in preparation for the hot melt implanting process.

+ Benefits and Features:

- » Highest yield, maximum machine uptime and short product changeover times lead to very low cost of ownership
- » High flexibility for all IC module types and sizes, including Dual Interface
- » In-house tool manufacturing, customized punching tool designs on request
- » Stand-alone system or integration into production line



Glue Tape
Lamination

For more technical
details please visit
our Website





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Management
System
ISO 9001:2015
ISO 14001:2015

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